

## REMARKS

This application has been carefully reviewed in light of the Office Action dated November 20, 2003. Claims 1, 9, 10, 13 to 16 and 18 are in the application, of which Claims 9, 10, 13 to 16 and 18 are withdrawn from consideration. Claims 1, 9, 14, 15 and 18 are the independent claims. Claims 2, 3, 5, 11, 12 and 17 have been cancelled without prejudice to or disclaimer of subject matter; and Claims 1, 9, 14, 15 and 18 have been amended. Reconsideration and further examination are respectfully requested.

Claims 1 to 3 were rejected under 35 U.S.C. § 103(a) over JP 10-337982 (JP '982) in view of U.S. Patent No. 6,630,370 (Kasahara). The rejection is respectfully traversed.

The present invention as recited by Claim 1 concerns a semiconductor device for transmitting information by using an induction field as a transmission medium. The semiconductor device includes (a) an IC chip for storing and processing information to be transmitted; (b) an IC chip supporting section for mounting the IC chip thereon; (c) a coil for generating the induction field; (d) connecting terminals provided at an end of the coil; (e) wires connecting the IC chip and the connecting terminals; (f) sheets of tape bonding and fixing a part of one side of the coil; and (g) a resin integrating the IC chip, the IC chip supporting section, the coil, the wires, the connecting terminals, and the sheets of tape with one another. The IC chip supporting section, the coil, and the connecting terminals are formed of the same metal plate that is patterned, and at least one side of the coil is exposed from a surface of the resin.

Thus, according to one feature of the invention as recited by Claim 1, at least one side of the coil is exposed from a surface of the resin.

JP '982 and Kasahara, either alone or in combination, are not seen to teach or suggest at least the foregoing feature.

With respect to JP '982, it is Applicants' understanding that the antenna coil (4) does not have a side exposed from a surface of the epoxy filler.

With respect to Kasahara, the plain coil (12) is bonded between two sheets of films (38), and as such, is not believed to have a side exposed from a surface of the resin. See col. 8, lines 20 to 51, and Fig. 8 of Kasahara.

Applicant therefore concludes that the applied documents do not teach or suggest the claimed invention either singly or in the combination proposed by the Office Action, and it is respectfully requested that the Section 103 rejection be withdrawn.

Claim 1 is believed to be generic to the species in non-elected Claim 18. Accordingly, examination of Claim 18 is respectfully requested once Claim 1 has received an indication of allowability. See MPEP §806.04(d).

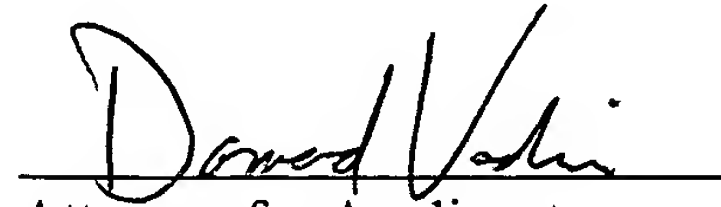
Non-elected method Claims 9, 14 and 15 have been amended to include all the features of elected product Claim 1. Accordingly, rejoinder of method Claims 9, 10 and 13 to 16 is respectfully requested, pursuant to MPEP § 821.04.

An Information Disclosure Statement was submitted on December 19, 2003. Consideration of the documents cited therein is respectfully requested.

No other matters being raised, the entire application is believed to be in condition for allowance, and such action is courteously solicited.

Applicant's undersigned attorney may be reached in our Washington, D.C. office by telephone at (202) 530-1010. All correspondence should continue to be directed to our below-listed address.

Respectfully submitted,

A handwritten signature in dark ink, appearing to read "Damond Vadnais", is written over a horizontal line.

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